

Sensors and Materials

Special Issue on CMOS Image Sensors

Call for Papers

CMOS image sensors have sustained impressive technological developments as well as growth in existing markets such as smartphones, automotive cameras, security and industrial cameras, and medical/scientific cameras. Developments have included sub-micron pixels, high dynamic range sensors, three-dimensional integration for small and efficient imaging systems on chips, sub-electron read noise pixels for single-photon imaging, and many others. This Special Issue calls for papers on a wide variety of CMOS image sensor technologies as well as designs of devices, circuits, and systems, and their materials.

Scope:

- CMOS image sensors and related technologies
- Application-specific image sensors
- Novel architectures, operations, and materials for imaging devices
- Devices imaging invisible phenomena (IR, UV, X-ray, high-energy particles, ions, etc.)
- Others

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Guest Editor: Mr. Hiroshi Ohtake (nanolux co., ltd.)

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If you have any questions, please feel free to contact the editorial staff at the address below.

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